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**Space systems — Semiconductor  
integrated circuits for space  
applications — Design requirements**

*Systèmes spatiaux — Circuits intégrés semi-conducteurs  
d'applications spatiales — Exigences de conception*



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## Introduction

Normative design requirements of semiconductor integrated circuits for space applications largely determine the reliability of an integrated circuit (IC) and its adaptability to space environment, thereby affecting the reliability of space systems. IC tests and experiments based on product specification only can provide a comprehensive evaluation of its reliability. Once applied to space systems, the design flaws will directly affect the implementation of aerospace engineering. The development of design requirements for semiconductor ICs for space applications can ensure its reliability and space suitability from its very source to meet the space application requirements.

